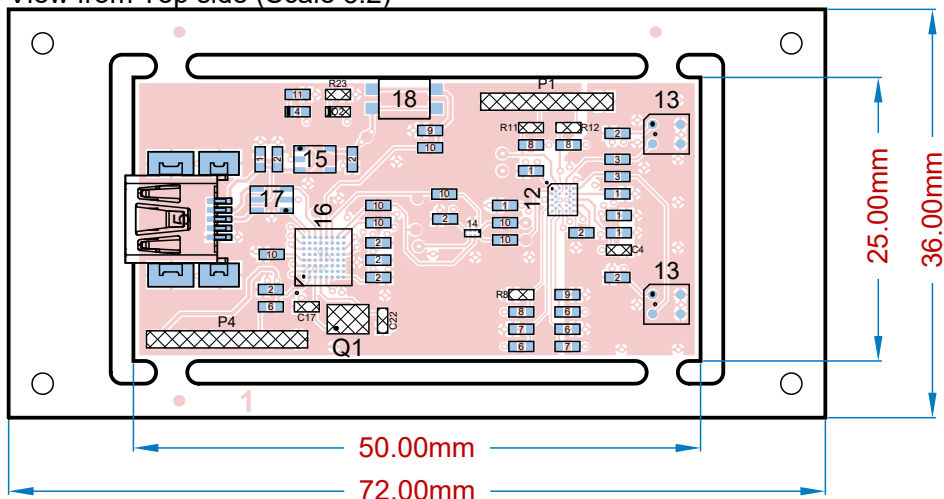
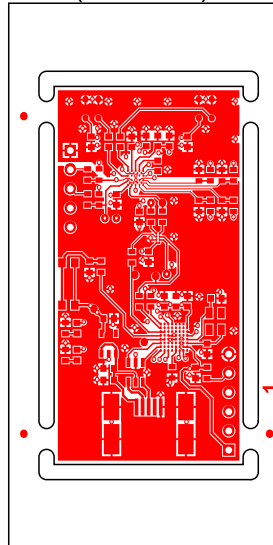


BR262 Host Module 1.1

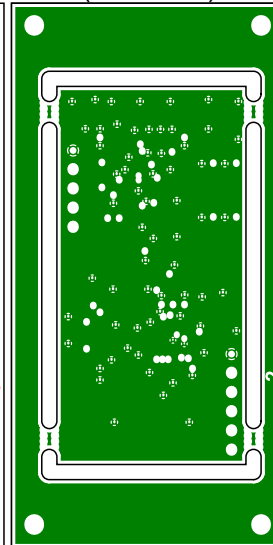
View from Top side (Scale 3:2)



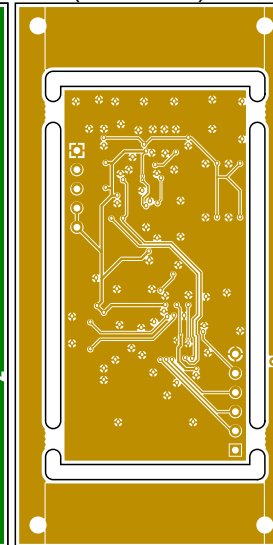
TOP (Scale 1:1)



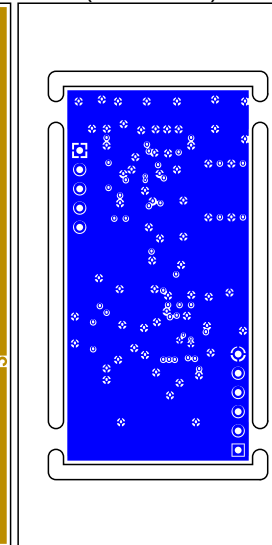
GND (Scale 1:1)



SIG (Scale 1:1)



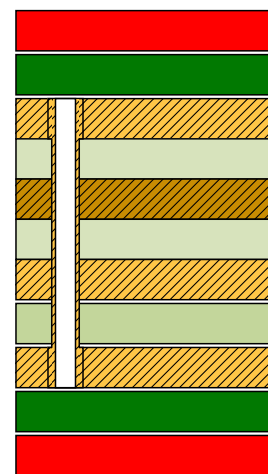
BOT (Scale 1:1)



Bill Of Materials

Line #	Designator	Comment	Quantity
1	C1, C2, C3, C5, C6, C12	CAP CER 1UF 6.3V X5R 0603	6
2	C7, C10, C13, C14, C15, C16, C18, C19, C20, C21	CAP CER 100NF 6.3V X7R 0603	10
3	C9, C11	CAP CER 10NF 10V X7R 0603	2
4	D1	LED SMD 0603	1
5	P3	MOLEX 67503-1230	1
6	R1, R3, R6, R16	RES SMD 100K OHM 1% 0.1W 0603	4
7	R2, R7	RES SMD 75K OHM 1% 0.1W 0603	2
8	R4, R9, R10	RES SMD 10K OHM 1% 0.1W 0603	3
9	R5, R21	RES SMD 39K OHM 1% 0.1W 0603	2
10	R13, R14, R15, R17, R18, R19, R24	RES SMD 47 OHM 1% 0.1W 0603	7
11	R22	RES SMD 100 OHM 1% 0.1W 0603	1
12	U1	BR262W26A103E1G	1
13	U2, U5	SPU0410HR5H-PB	2
14	U3	ADAU7002ACBZ	1
15	U4	LP5907MFX-3.3/NOPB	1
16	U6	STM32L052R8H6	1
17	U7	USBLC6-2SC6	1
18	X1	WE434351045816	1

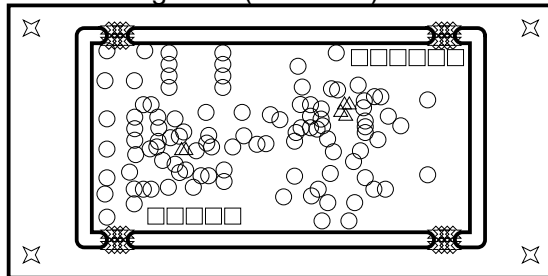
Layer Stack Legend



Material	Layer	Thickness
	Top Overlay	
Surface Material	Top Solder	0.010mm
Copper	TOP	0.035mm
Prepreg		0.140mm
Copper	GND	0.035mm
Core		1.200mm
Copper	SIG	0.035mm
Prepreg		0.140mm
Copper	BOT	0.035mm
Surface Material	Bottom Solder	0.010mm
	Bottom Overlay	

Total thickness: 1.640mm

Drill Drawing View (Scale 1:1)



Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
▽	6	0.20mm	Plated	
○	104	0.30mm	Plated	
☆	32	0.50mm	Non-Plated	
□	11	0.90mm	Plated	
✱	4	2.00mm	Non-Plated	
	157 Total			